

FRED Ultrafast Soft Recovery Diode 30A / 600V



FEATURES

- Ultrafast recovery
- Ultrasoft recovery
- Ver low I_{RRM}
- Ver low Q_{rr}
- Compliant to RoHS
- Designed and qualified for industrial level
- Planar FRED Chip

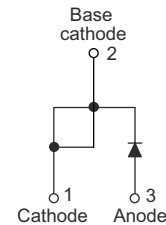
BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION

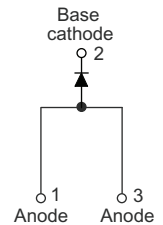
30ETU06 is a state of the art ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600V and 30A continuous current, the 30ETU06 is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the FRED product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to “snap-off” during the t_D portion of recovery. The FRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These FRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The FRED 30ETU06 is ideally suited for applications in power supplies and conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

30ETU06



TO-220AC Modified

30ATU06



TO-220AB

PRODUCT SUMMARY

V_R	600 V
V_F at 30A at 25 °C	1.7 V
$I_{F(AV)}$	30 A
t_{rr} (typical)	25 ns
T_J (maximum)	175 °C
Q_{rr}	130 nC
$di_{(rec)M}/dt$	260 A/ μ s

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	V_R		600	V
Maximum continuous forward current	I_F	$T_C = 116\text{ °C}$	30	A
Single pulse forward current	I_{FSM}	$T_C = 25\text{ °C}$	300	
Maximum repetitive forward current	I_{FRM}		110	
Maximum power dissipation	P_D	$T_C = 25\text{ °C}$	145	W
		$T_C = 100\text{ °C}$	57	
Operating junction and storage temperature range	T_J, T_{Stg}		- 55 to 175	°C

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ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V _{BR}	I _R = 100 μA	600	-	-	V
Maximum forward voltage	V _{FM}	I _F = 30 A	-	1.40	1.70	
		I _F = 60 A	-	1.75	2.0	
Maximum reverse leakage current	I _{RM}	V _R = V _R rated	-	1.0	10	μA
		T _J = 150 °C, V _R = V _R rated	-	20	500	
Junction capacitance	C _T	V _R = 200V	-	35	-	pF
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8	-	nH

DYNAMIC RECOVERY CHARACTERISTICS PERLEG (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t _{rr}	I _F = 0.5A, I _R = 1.0A, I _{RR} = 0.25A (RG#1 CKT)	-	32	38	ns
		I _F = 1.0 A, di _F /dt = 100 A/μs, V _R = 30 V, T _J = 25 °C	-	25	-	
	t _{rr1}	T _J = 25 °C	-	30	60	
	t _{rr2}	T _J = 125 °C	-	175	125	
Peak recovery current	I _{RRM1}	T _J = 25 °C	-	3	6.0	A
	I _{RRM2}	T _J = 125 °C	-	6	10	
Reverse recovery charge	Q _{rr1}	T _J = 25 °C	-	130	180	nC
	Q _{rr2}	T _J = 125 °C	-	485	600	
Peak rate of fall of recovery current during t _b	di _{(rec)M} /dt1	T _J = 25 °C	-	260	-	A/μs
	di _{(rec)M} /dt2	T _J = 125 °C	-	160	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C
Thermal resistance, junction to case	R _{thJC}		-	0.5	0.8	K/W
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	80	
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and gerased	-	0.4	-	
Weight			-	2	-	g
			-	0.07	-	oz.
Mounting torque			6 (5)	-	12 (10)	kgf . cm (lbf . in)
Marking device		Case style TO-220AC Modified	30ETU06			
		Case style TO-220AB	30ATU06			

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Fig.1 Typical forward voltage drop characteristics

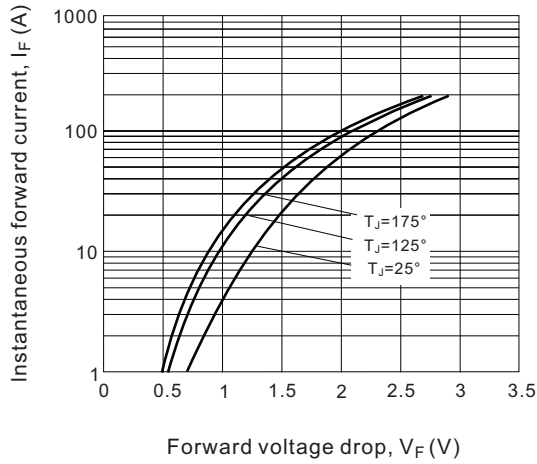


Fig.2 Typical values of reverse current vs. reverse voltage

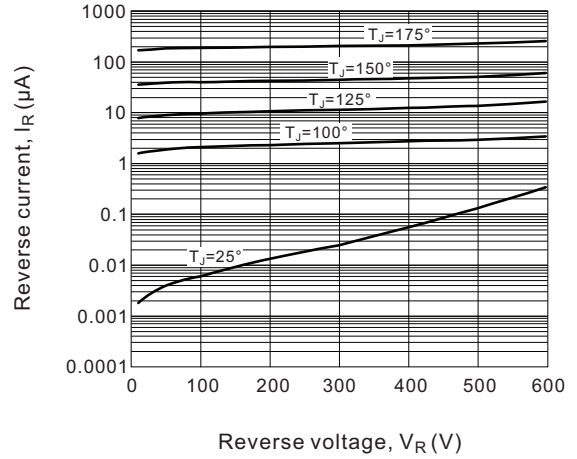


Fig.3 Typical junction capacitance vs. reverse voltage

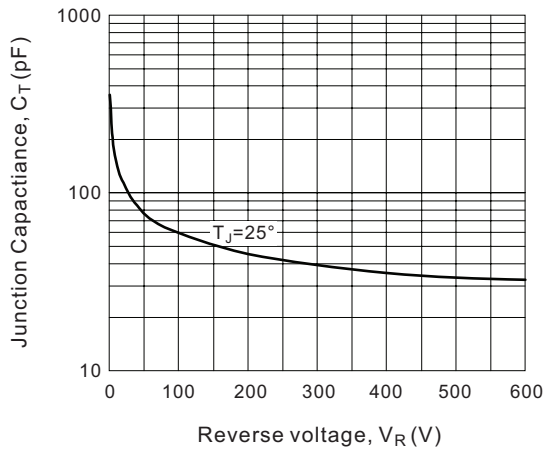


Fig.4 Junction capacitance vs. reverse voltage

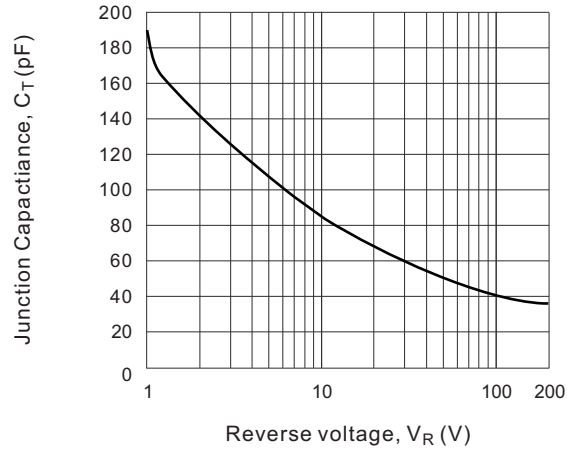
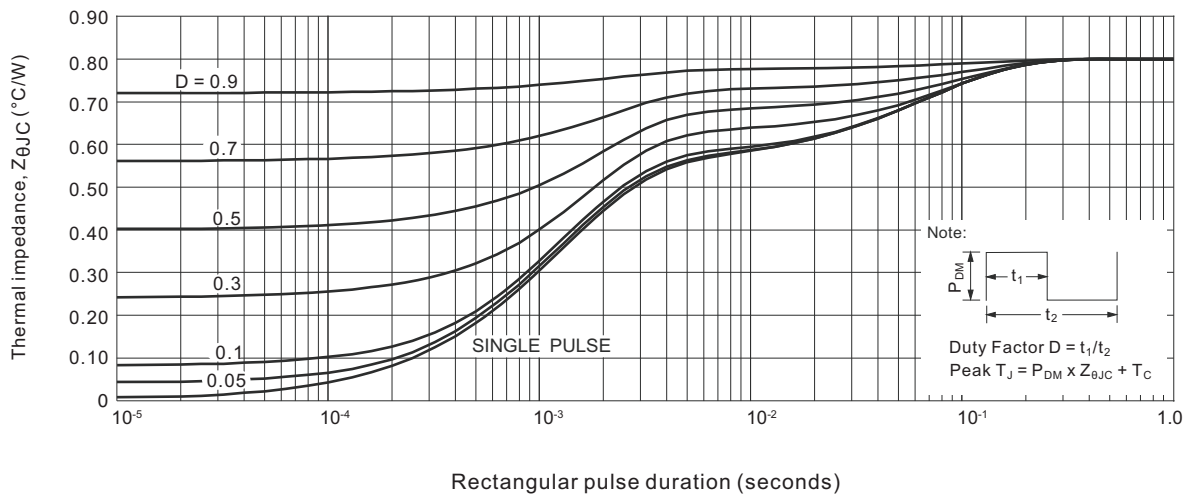


Fig.5 Maximum effective transient thermal impedance, junction-to-case vs. pulse duration



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Fig.6 Max. allowable case temperature Vs. average forward current

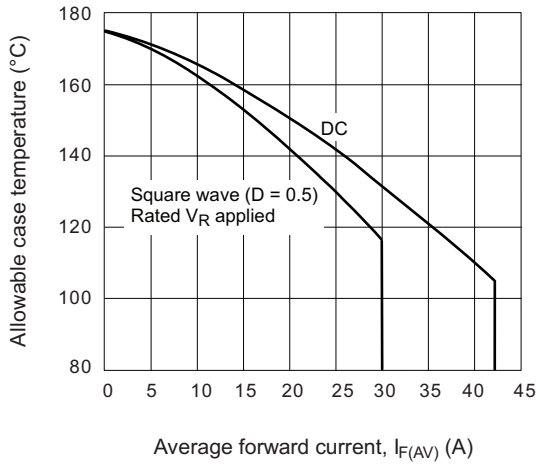


Fig.7 Reverse recovery time vs. current rate of change

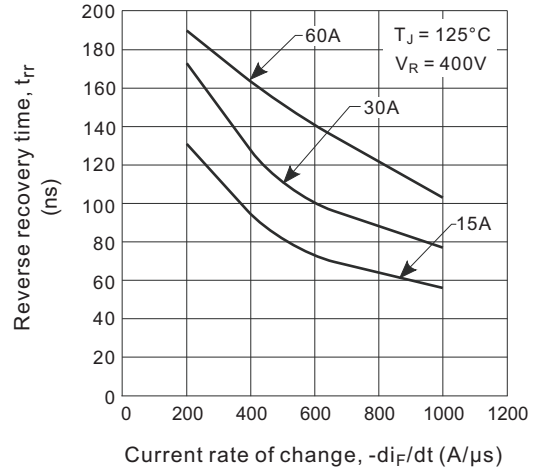


Fig.8 Maximum average forward current vs. case temperature

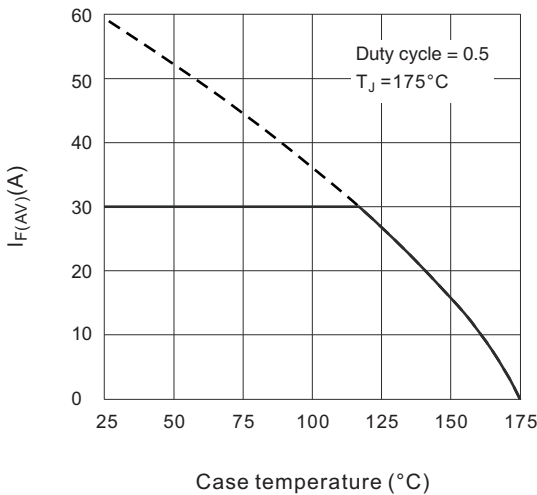
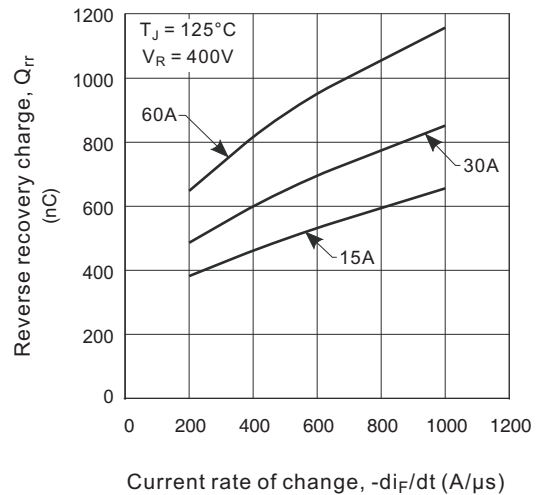


Fig.9 Reverse recovery charge vs. current rate of change



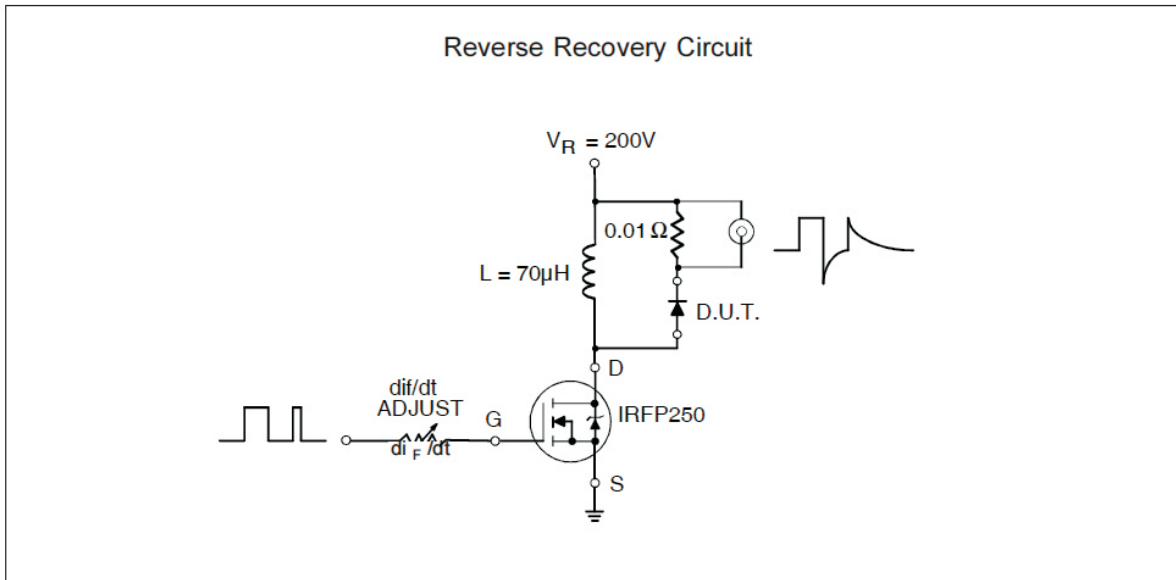
Ordering Information Table

Device code

30	E	T	U	06
①	②	③	④	⑤

- ① - Current rating (30 = 30A)
- ② - Single Diode
- ③ - TO-220AC Modified or TO-220AB
- ④ - Ultrafast Recovery
- ⑤ - Voltage Rating (06 = 600 V)

E = 2 pins
 A = 3 pins

Fig.9 Reverse recovery parameter test circuit


(3) Formula used: $T_c = T_j - (P_d + P_{d_{REV}}) \times R_{thJC}$;

P_d = Forward Power Loss = $I_{F(AV)} \times V_{FM} @ (I_{F(AV)} / D)$ (see Fig. 6);

$P_{d_{REV}}$ = Inverse Power Loss = $V_{R1} \times I_R (1 - D)$; $I_R @ V_{R1} = 80\%$ rated V_R

Fig.10 Reverse recovery waveform and definitions
